



(51) International Patent Classification:

H01L 21/687 (2006.01) B23K 26/38 (2006.01)
H01L 21/683 (2006.01) B23K 26/142 (2014.01)
H01L 21/67 (2006.01)

(21) International Application Number:

PCT/US2025/013625

(22) International Filing Date:

29 January 2025 (29.01.2025)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/627,679 31 January 2024 (31.01.2024) US
19/032,966 21 January 2025 (21.01.2025) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UY, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,

(54) Title: SUBSTRATE HOLDER

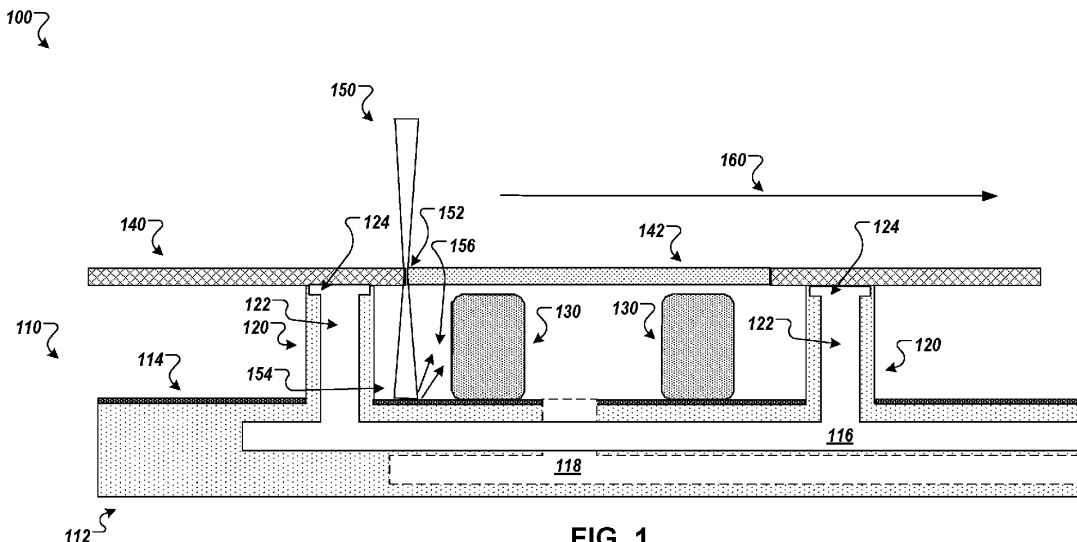


FIG. 1

(57) Abstract: A substrate holder includes a chuck base forming a chucking vacuum line and a particle vacuum line. The particle vacuum line is to extract particles produced from substrate processing. The substrate holder further includes one or more chuck posts extending from an upper surface of the chuck base. The chucking vacuum line is routed through the one or more chuck posts to chuck a substrate. The substrate holder further includes one or more die collect components disposed on the upper surface of the chuck base. A device is to be supported by at least one of the one or more die collect components responsive to being cut from the substrate.

[Continued on next page]

RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

- *with international search report (Art. 21(3))*